

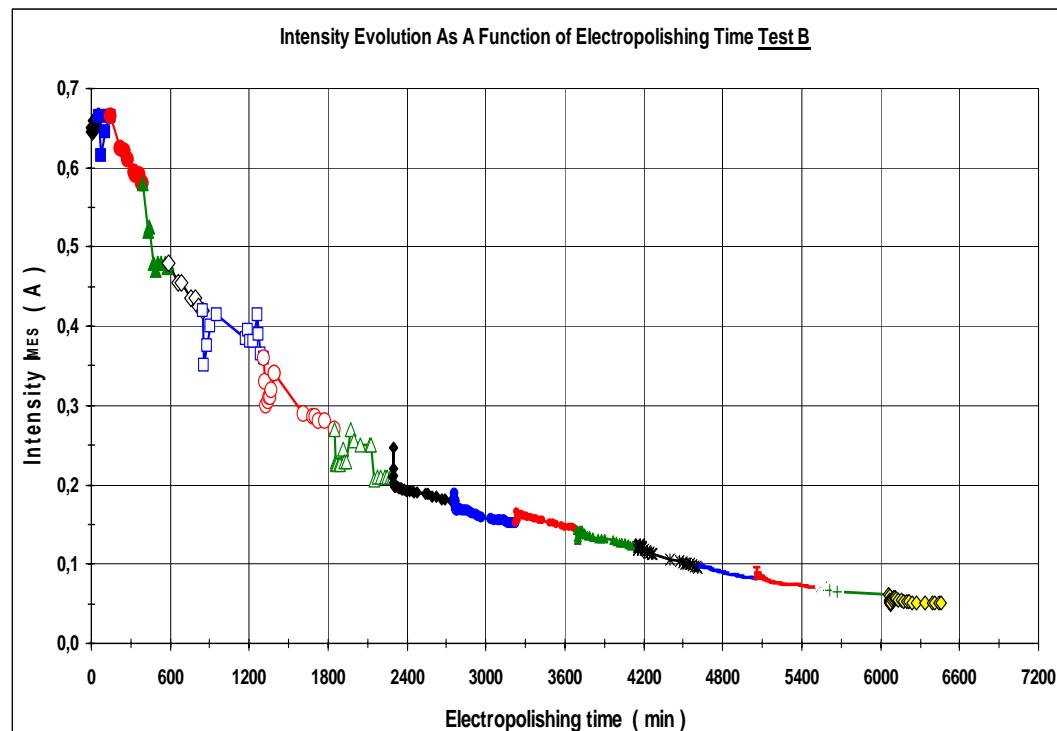
# Optimization of Electropolishing

***Main issues :***

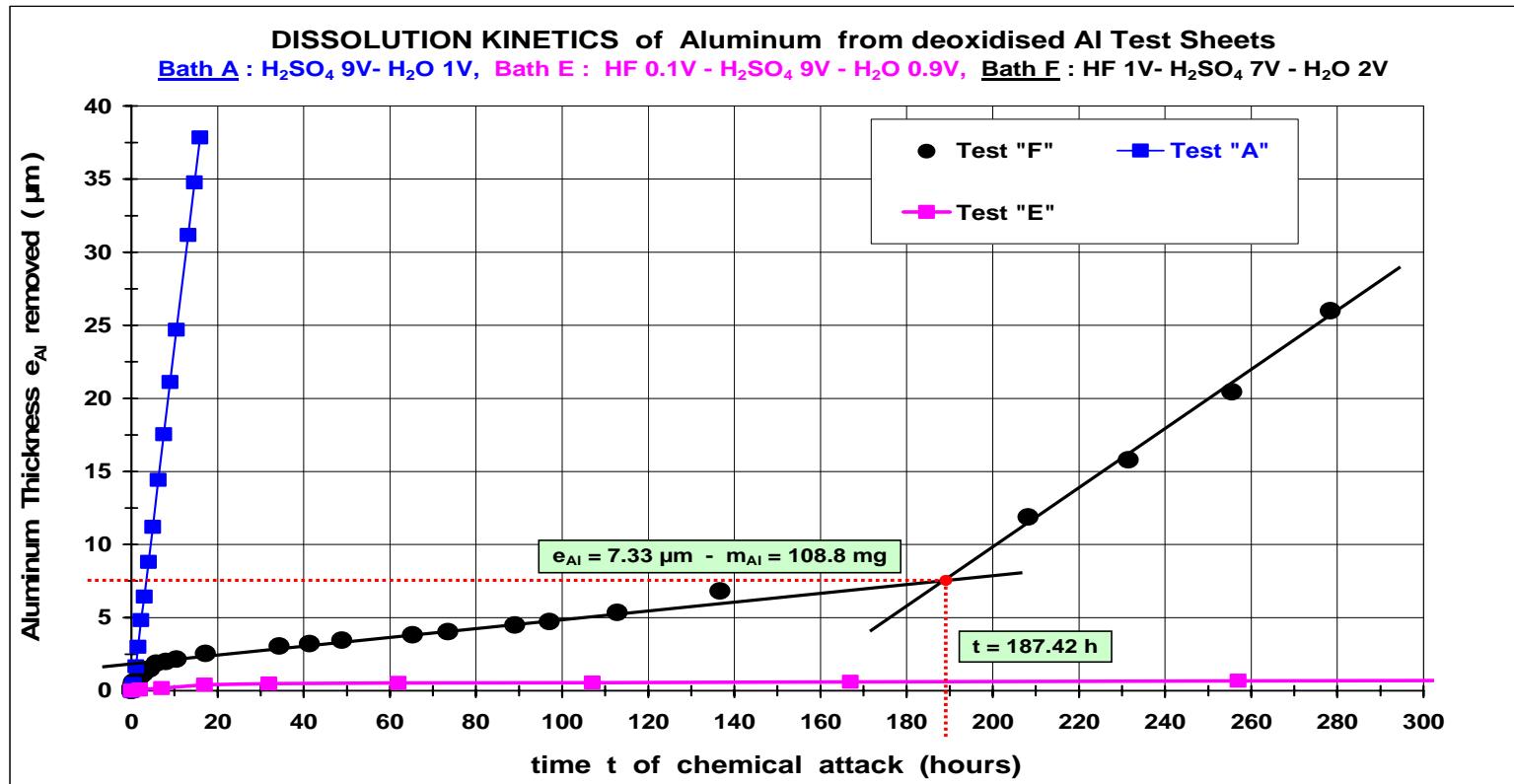
- ***Aging vs impurity content.***
- ***Efficiency (etching rate, life-time, surface state)***

# Aging Of The Bath

- Drop in the polishing speed.
- Deterioration of samples' surface.
- Changes in intensity oscillations.
- Aluminum corrosion, S and H<sub>2</sub>S production



# Passivity of alumina (without bias)



Test #	Volumic composition				Sulfur synthesis	
	HF	$\text{H}_2\text{SO}_4$	$\text{H}_2\text{O}$ add <sup>d</sup>	Total Volume	Time (minutes)	Sulfur mass (g)
A	0	9 V	1V	10 V	955	184,2
E	0,1 V	9 V	0,9 V	10 V	5930	9,9
F	1 V	7 V	2 V	10 V	16705	29,1

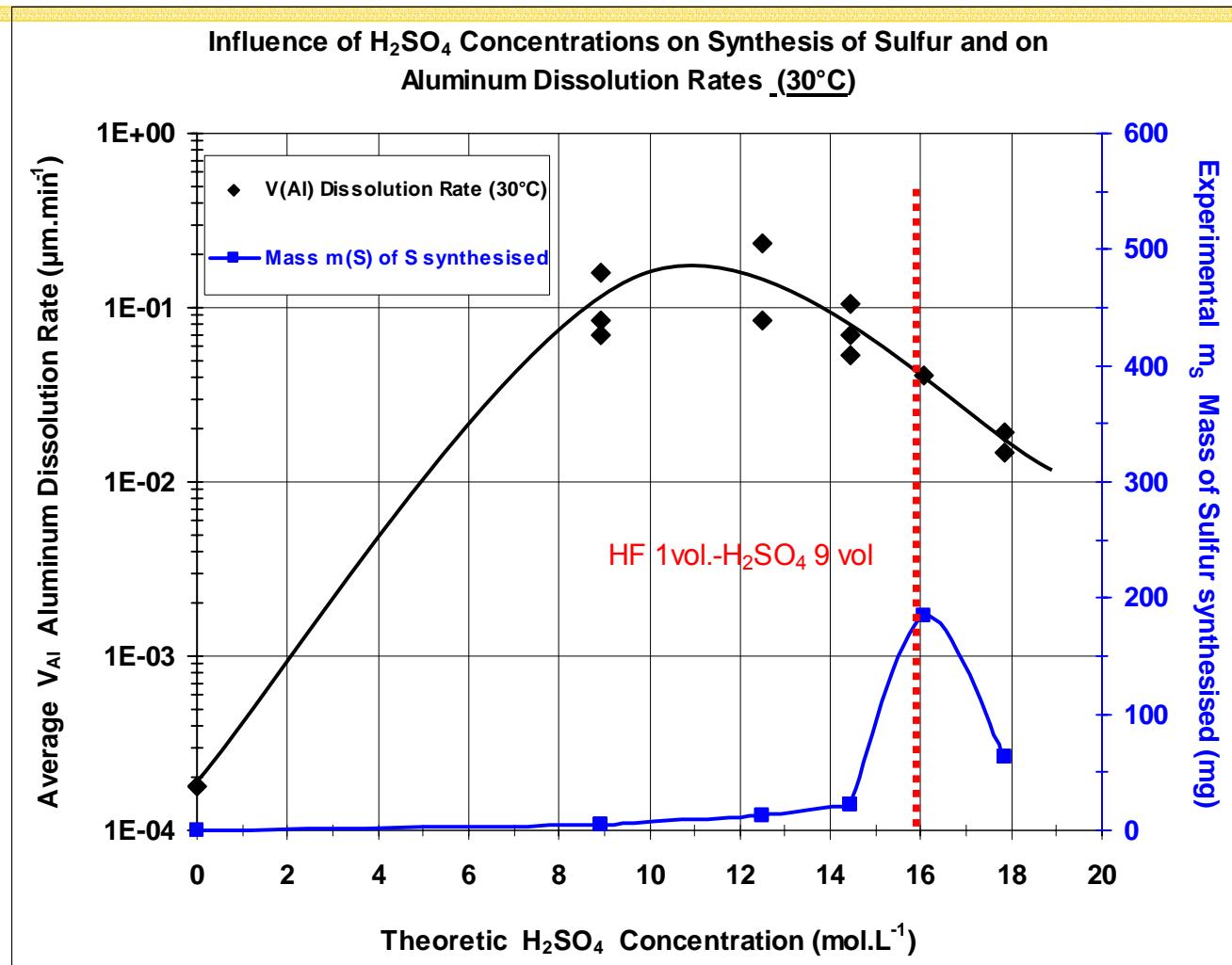
High  $\text{H}_2\text{SO}_4$  content

Same  $\text{H}_2\text{SO}_4$  Content, slight add<sup>n</sup> of HF

Less  $\text{H}_2\text{SO}_4$  content, higher of HF !?

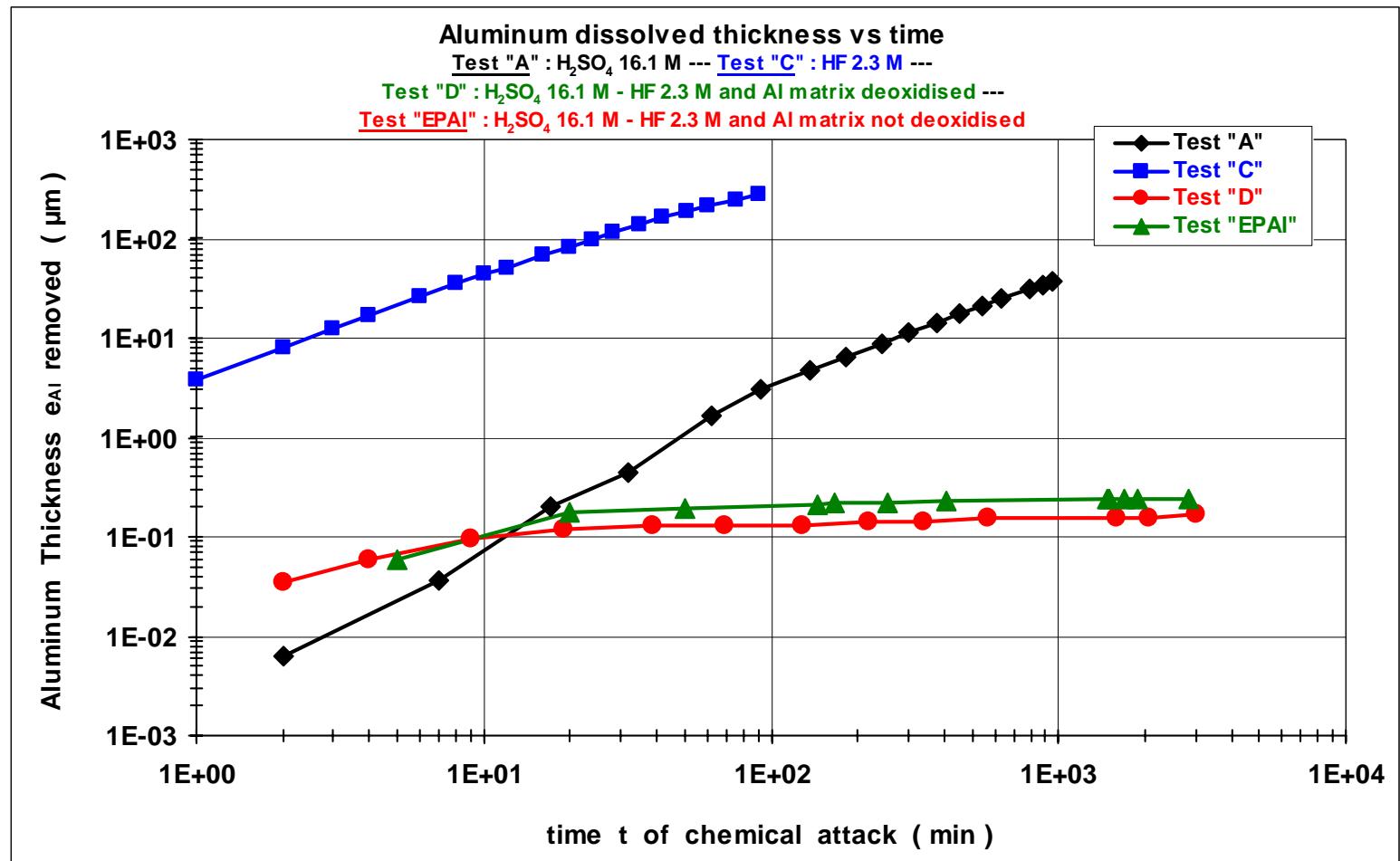
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# Aluminum corrosion, S and H<sub>2</sub>S production



Lower content of H<sub>2</sub>SO<sub>4</sub> reduces S production but increases Al corrosion (± acceptable !)

# Passivation of Aluminum



Still corrosion is far more lower than in separated acids

Aluminum is etched in each concentrated pure acids

- A few quantity of the other acid or dilution is enough to slow down drastically the dissolution of Al inside EP solution.
- Sulfur and  $\text{H}_2\text{S}$  is produced at high  $\text{H}_2\text{SO}_4$  concentration. S appears also when HF is reduced due to evaporation or reaction => add HF !?

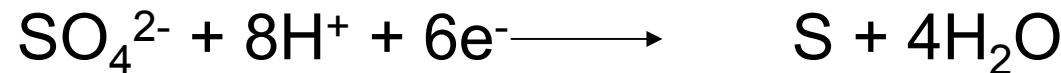
What is going on with bias ?

## Reduction of $\text{SO}_4^{2-}$ at the cathode under bias

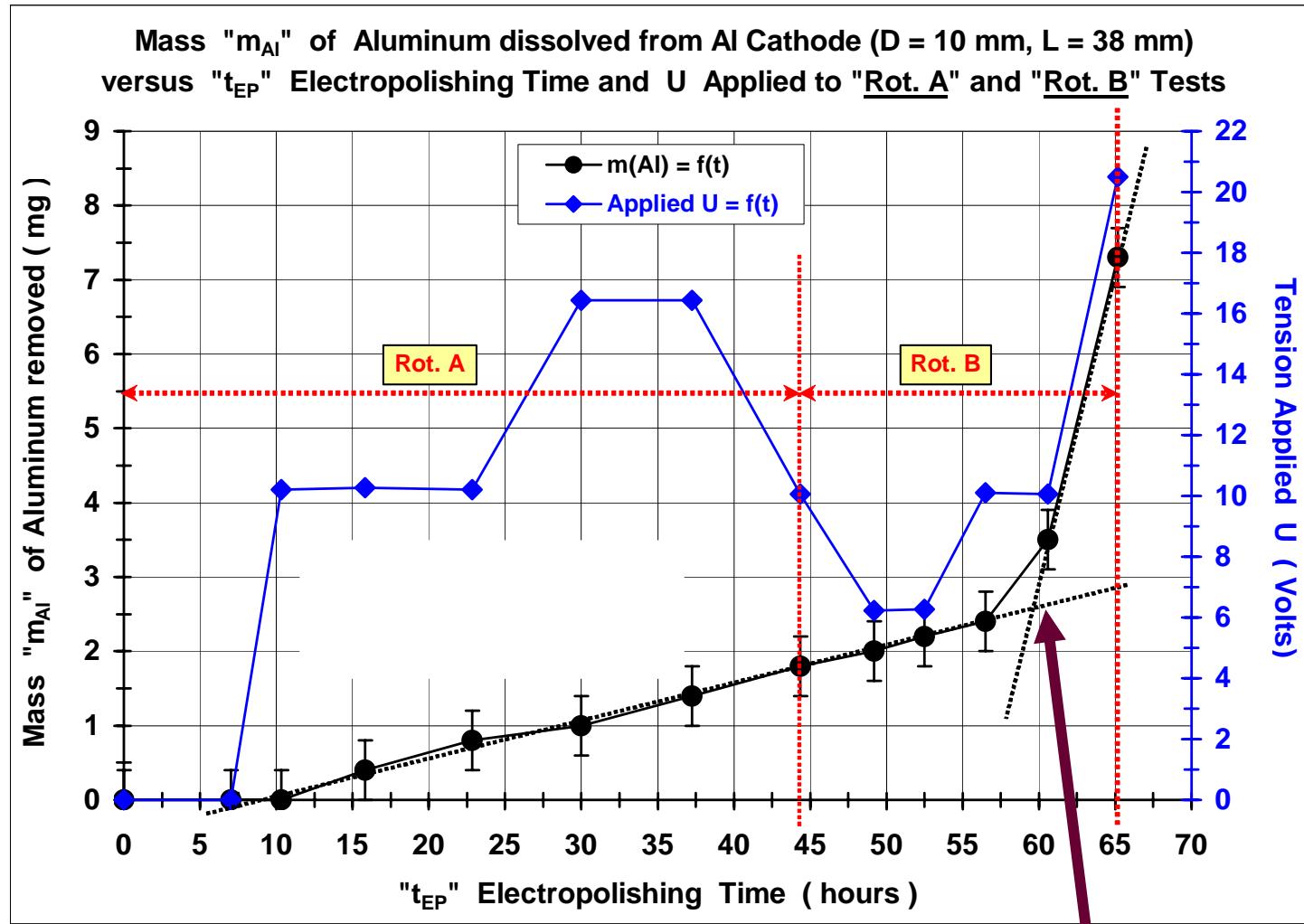
- slow but continuous corrosion of Al
- high quantity of S

Test\ sulfur production	$M_s$ calculated (compared to Al dissol <sup>n</sup> )(mg )	Measured $M_s$ (mg)
Rotanodes A	1,07	21,1
Rotanodes B	3,27	113,8

Additional formation of sulfur at cathode



# Cathode corrosion under bias



Corrosion becomes important when HF has reduced due to reaction + evaporation

## Without bias

- HF prevents S synthesis in presence of  $\text{H}_2\text{SO}_4$
- $\text{H}_2\text{SO}_4$  hinders Al dissolution in presence of HF
- Active dissolution of Al and production of S when HF decreases (evaporation, reaction)

## With bias:

- Synthesis of S and corrosion of aluminum cannot be hindered
- They can be reduced ( $\uparrow \text{HF}$ ,  $\uparrow \text{H}_2\text{O}$ ,  $\downarrow \text{H}_2\text{SO}_4$ )

## Conclusion 1

S is not soluble in H<sub>2</sub>O : rinsing process

- works in ethanol, but not very effective
- is very effective in chloroform, but safety issues

Rinsing process must be improved

Aluminum :

- Is slightly dissolved in acidic mixture
- keeps in the form of Al<sup>3+</sup> salts

Rinsing process must be improved

+ Change in EP bath composition : ↑ HF, ↑ H<sub>2</sub>O

# Aging effect on samples' surface

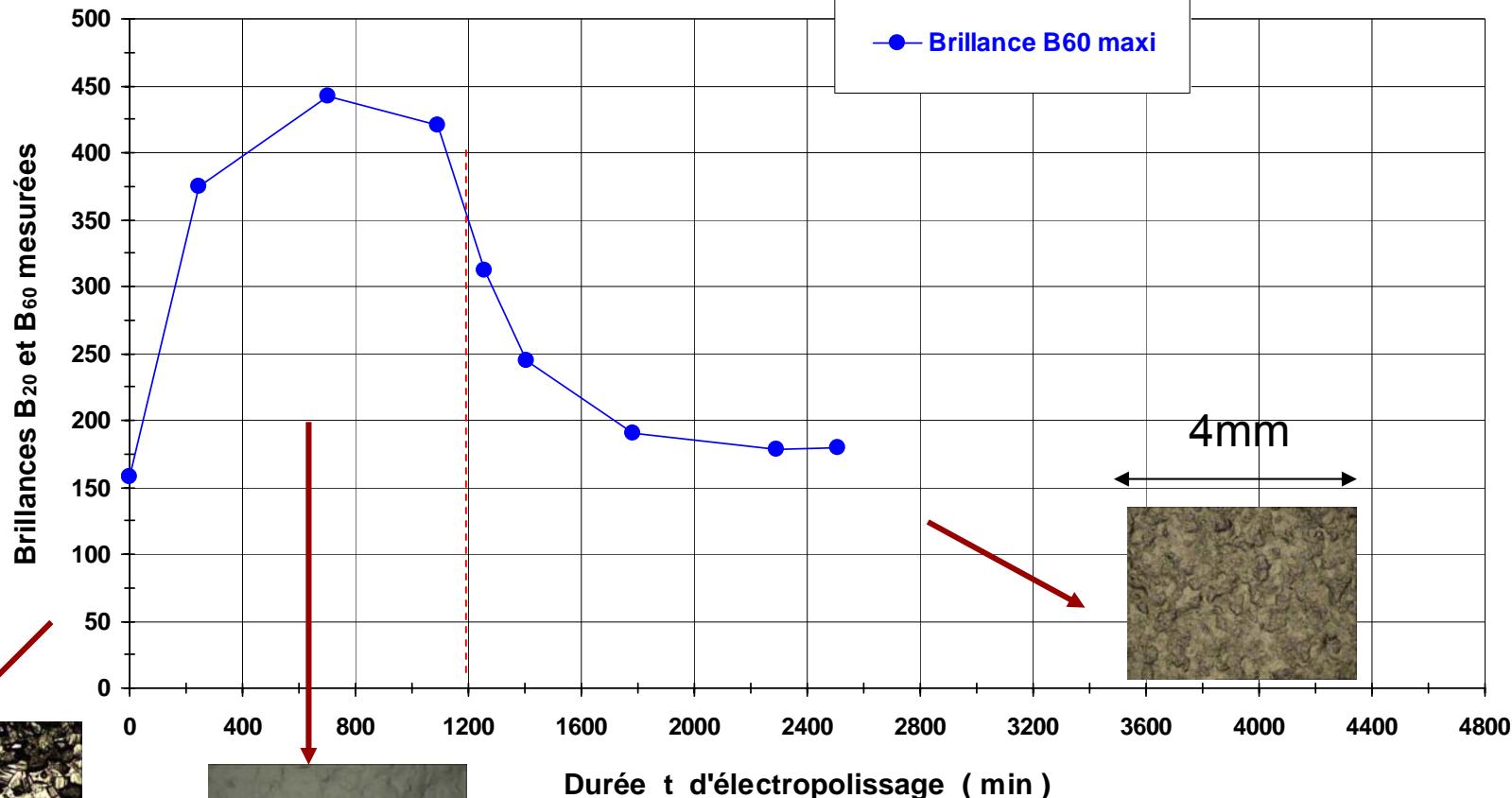
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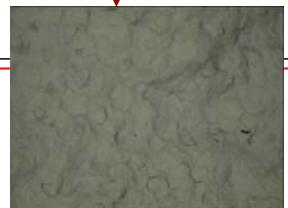
saclay

Evolution des Brilles  $B_{20}$  et  $B_{60}$  de la Plaque Nb au Test A 1V-9V 14 Volts

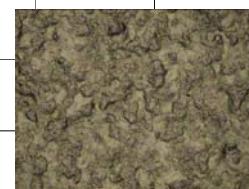
14 V



4mm

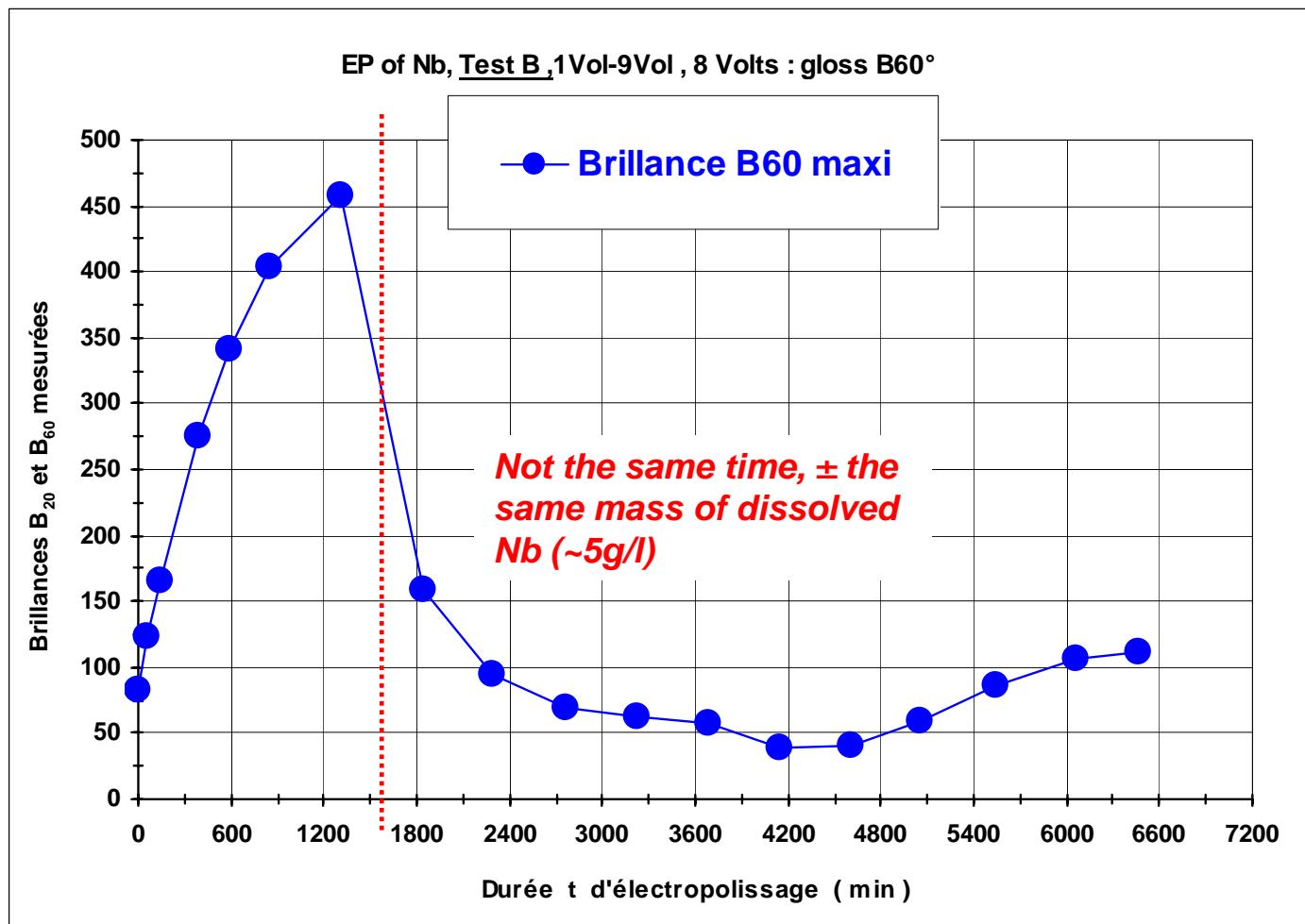


4mm



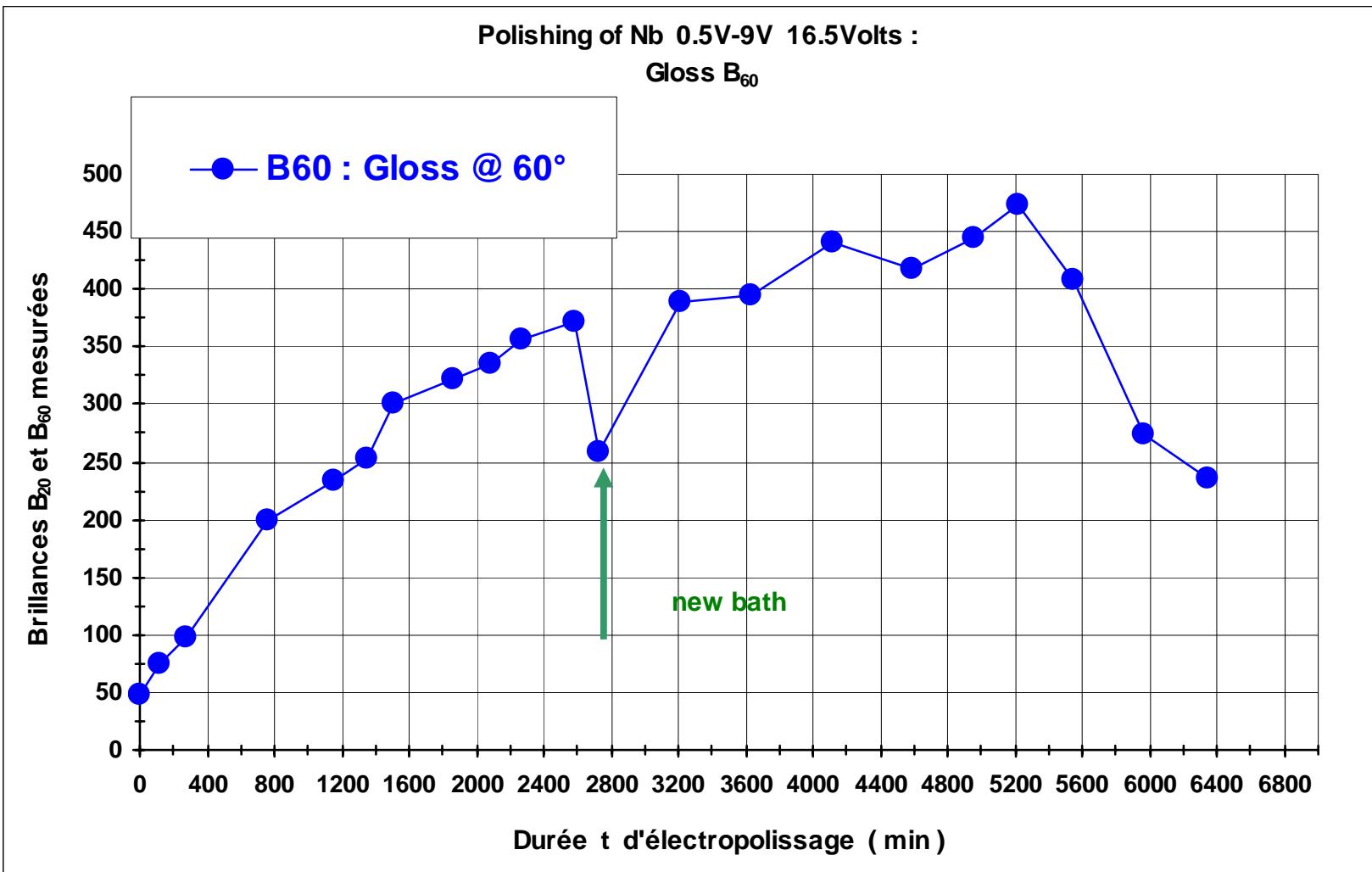
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## Aging of bath 2)



Does the Nb content of the solution matters ? (EP bath should be changed more often ?)

# Changing for a fresh mixture (same sample)



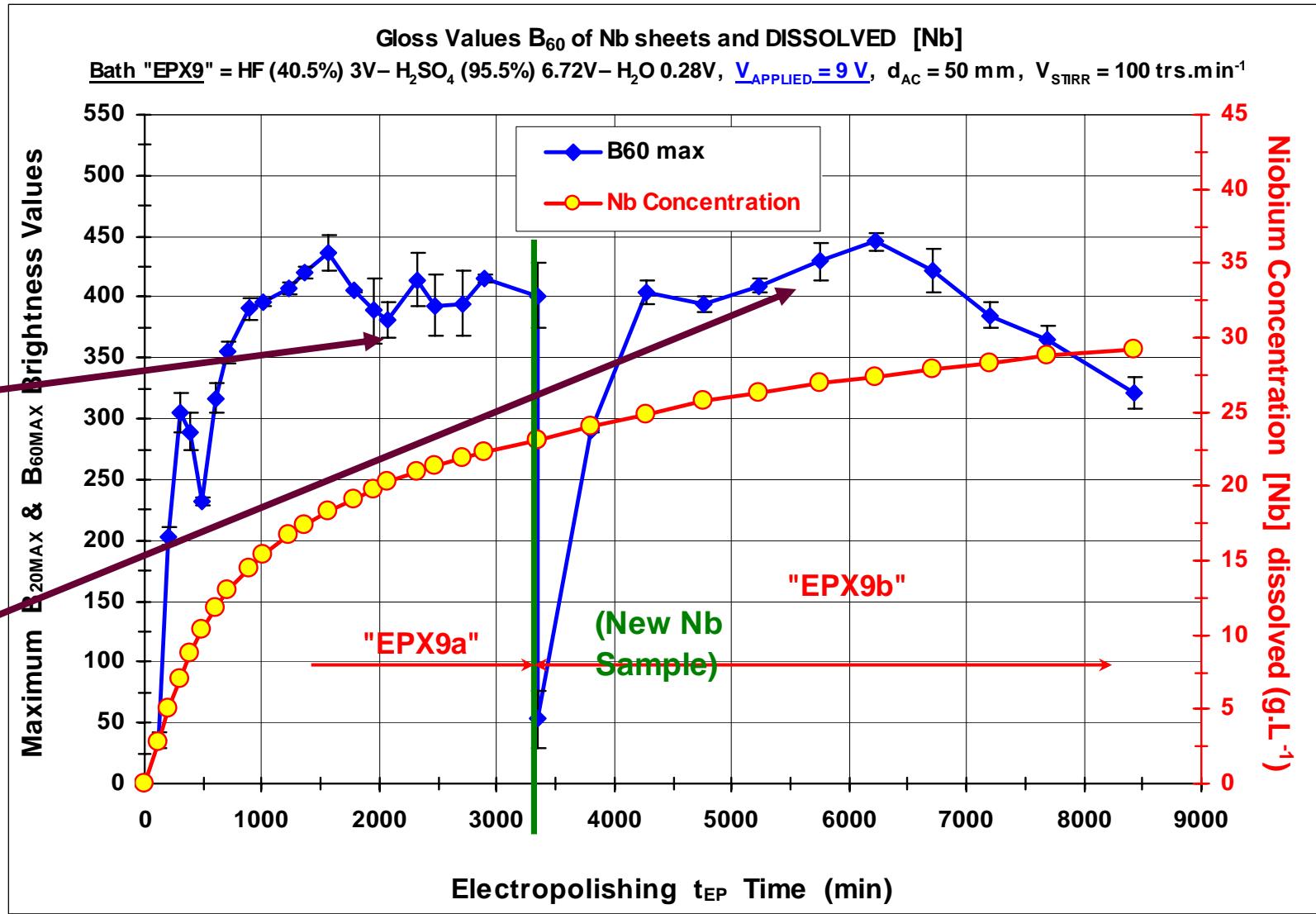
Gloss can be further improved with a fresh bath

# Higher HF content / Changing for a fresh sample

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Nb content ~ 23g/l

Nb content ~ 28g/l !!!



## Enhance HF and or H<sub>2</sub>O ?

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cea

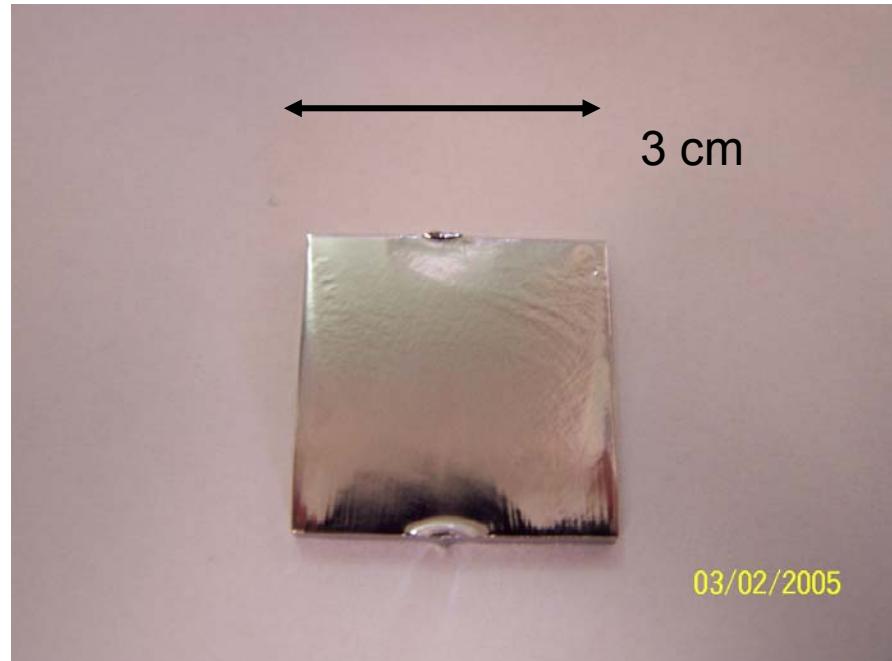
saclay

e.g. : HF 3 Vol. + H<sub>2</sub>SO<sub>4</sub> 6.72 vol + H<sub>2</sub>O 0.28 Vol :

- Not « polishing », but « active dissolution \* »
- High dissolution rate, lower potential
- Long lasting (Nb >> 25 g/ l and still B<sub>60</sub> = OK)
- Very glossy, but some ripples

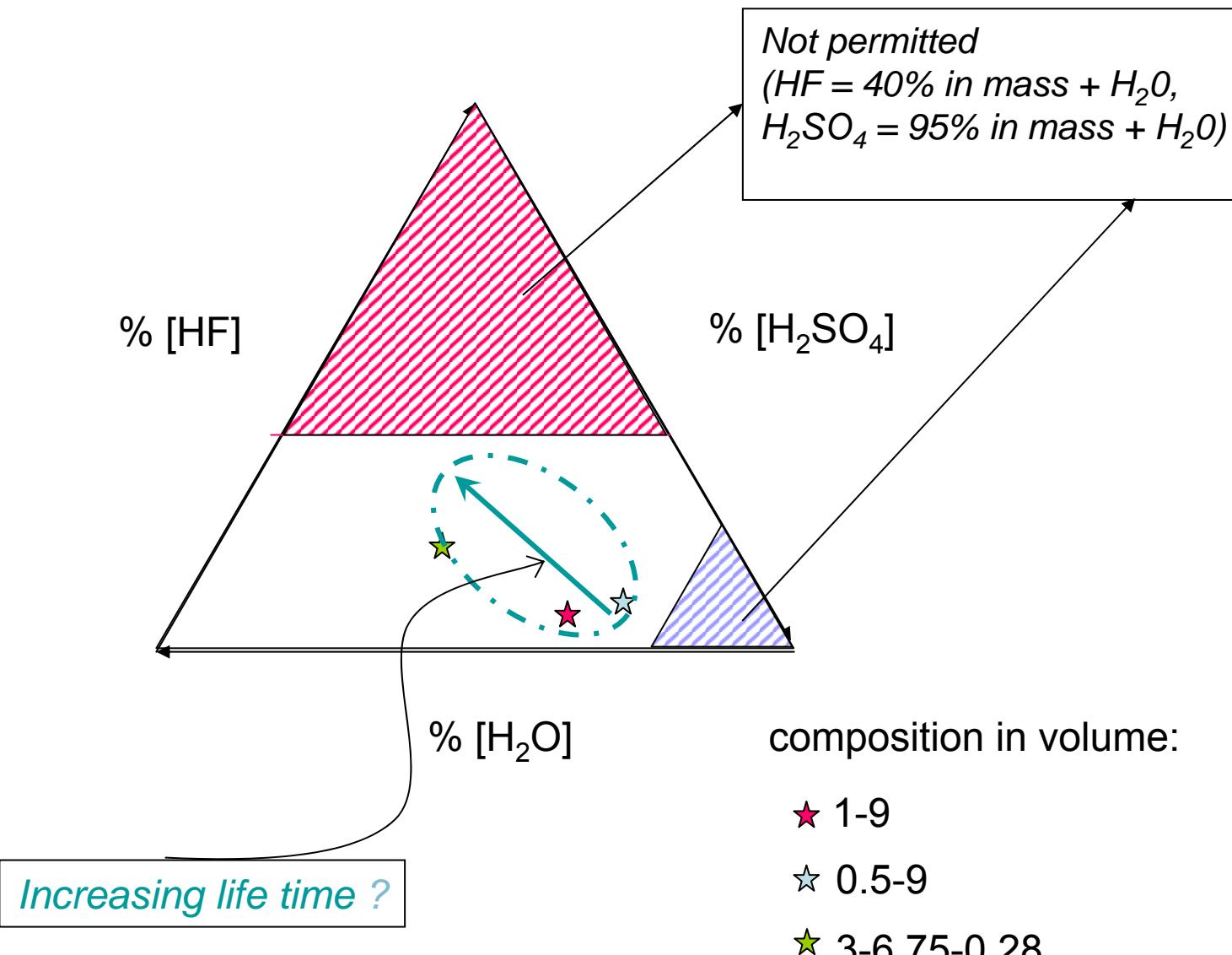
Acceptable ?

\* No plateau in th E=f(V) curve



# Possible compositions

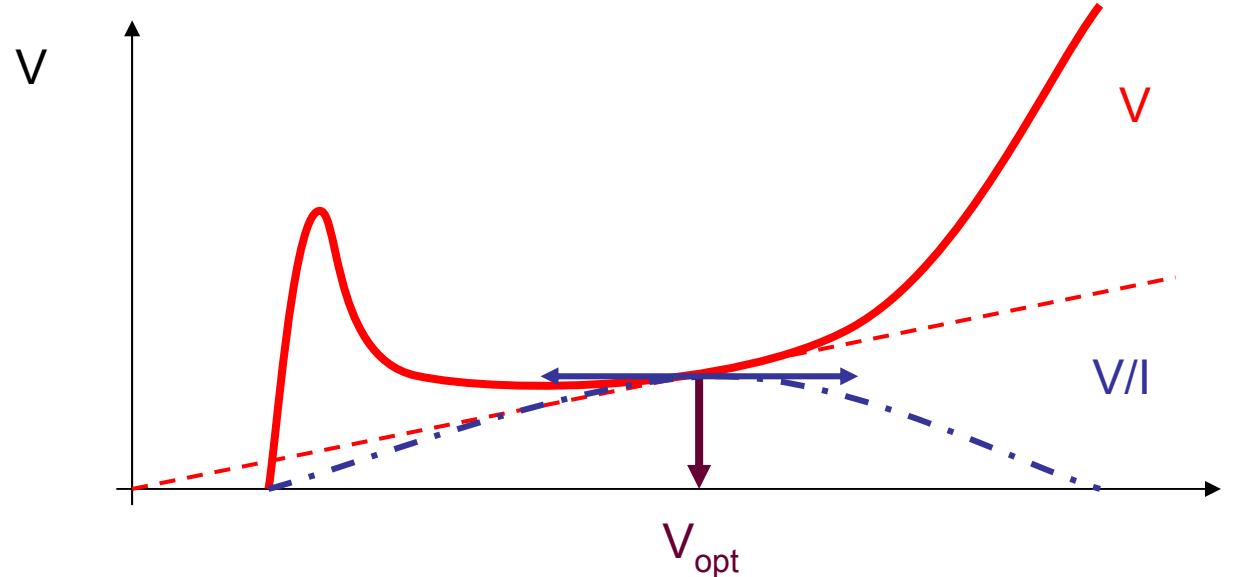
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Literature says :

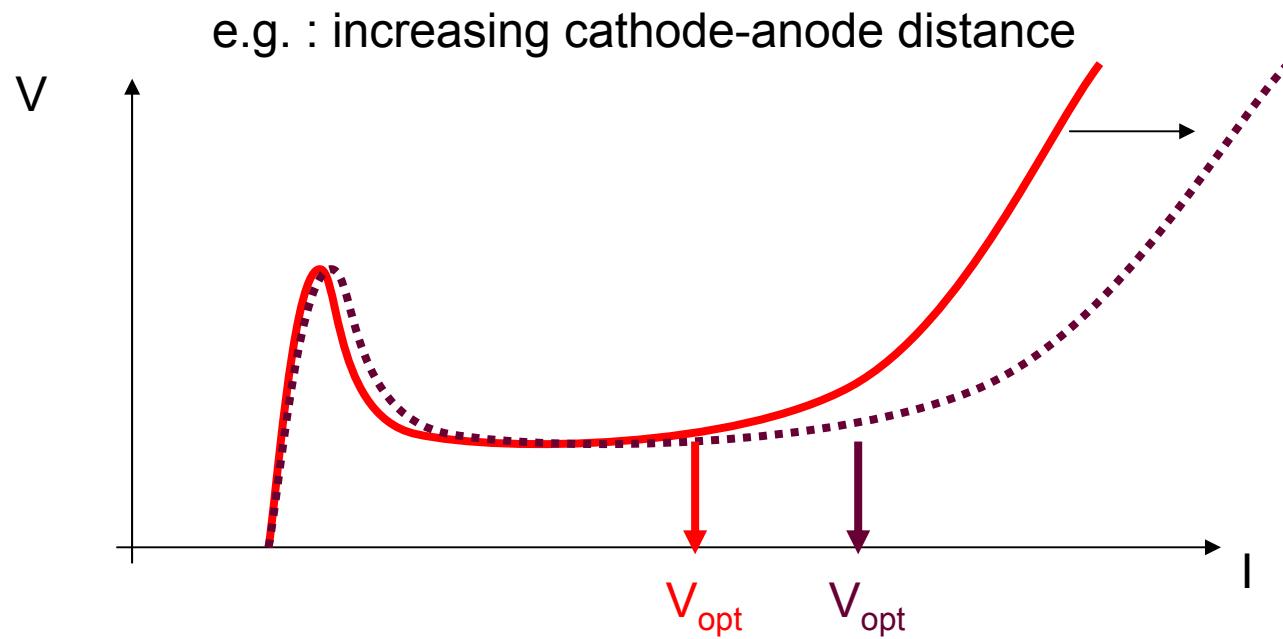
*Polishing = plateau in the  $I=f(V)$  curve + diffusion limitation*

=> 1st order criteria : « ideal V » @ the highest cell impedance



The  $I=f(V)$  curve depends on the characteristics of the «Circuit» (Geometry, field repartition, ...)

=> The  $I=f(V)$  curve must be determined in the real situation !!!!!



## Conclusion

- Increasing HF, H<sub>2</sub>O and decreasing H<sub>2</sub>SO<sub>4</sub> seems interesting in term of increase life time and efficiency of polishing bath, as well as reducing Sulfur content. It also allows to reduce bias, and possibly power.
- Al corrosion cannot be hindered, but is low and can be acceptable.
- Decision must be made between medium surface state but long lasting EP bath composition, and better surface state with lower life time etc.

=> test cavities with new bath composition !